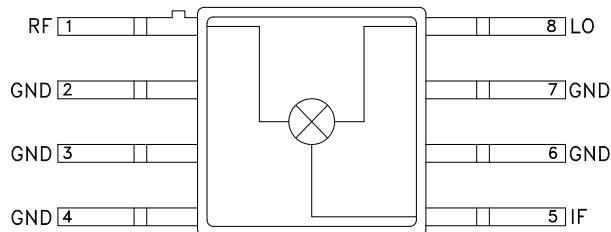



**GaAs MMIC SMT DOUBLE-BALANCED MIXER, 4 - 8 GHz**
**Typical Applications**

The HMC129G8 is ideal for:

- UNII & HiperLAN
- Military & Space
- Test Equipment

**9**
**MIXERS - DBL-BAL - SMT**
**Functional Diagram**

**Features**

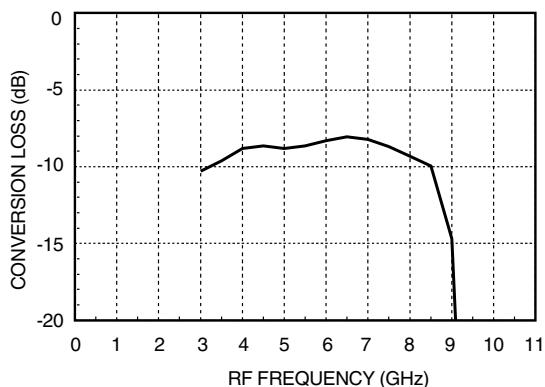
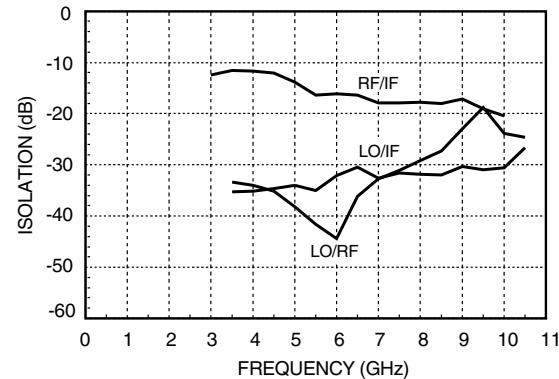
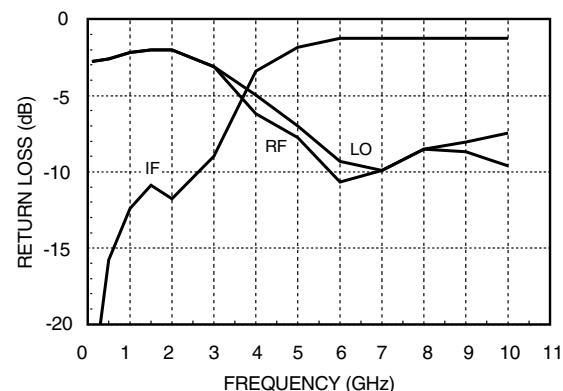
- Conversion Loss: 8 dB
- LO to RF and IF Isolation: 30 dB
- Small Size, No DC Bias Required

**General Description**

The HMC129G8 is a miniature double-balanced mixer in a hermetic surface mount package that can be used as an upconverter or downconverter. The device is a passive diode/balun type mixer with high dynamic range. Noise figure is essentially equal to the conversion loss. The mixer can handle larger signal levels than most active mixers due to the high third order intercept. MMIC implementation provides exceptional balance in the circuit resulting in high LO/RF and LO/IF isolations.

**Electrical Specifications,  $T_A = +25^\circ C$ , LO Drive = +15 dBm**

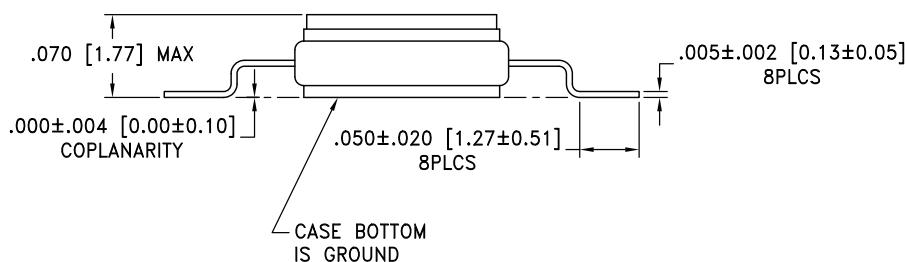
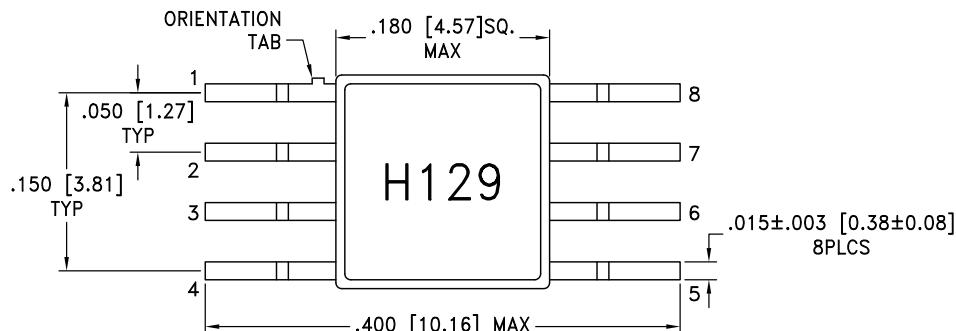
Parameter	Min.	Typ.	Max.	Units
Frequency Range, RF & LO		4.0 - 8.0		GHz
Frequency Range, IF		DC - 3		GHz
Conversion Loss		8	10	dB
Noise Figure (SSB)		8	10	dB
LO to RF Isolation	20	30		dB
LO to IF Isolation	20	30		dB
IP3 (Input)	13	18		dBm
IP2 (Input)	35	40		dBm
1 dB Gain Compression (Input)	5	10		dBm


**GaAs MMIC SMT DOUBLE-BALANCED MIXER, 4 - 8 GHz**
**Conversion Loss**

**Isolation**

**Return Loss**

**Distortion and 1dB Compression  
versus LO Drive Level**

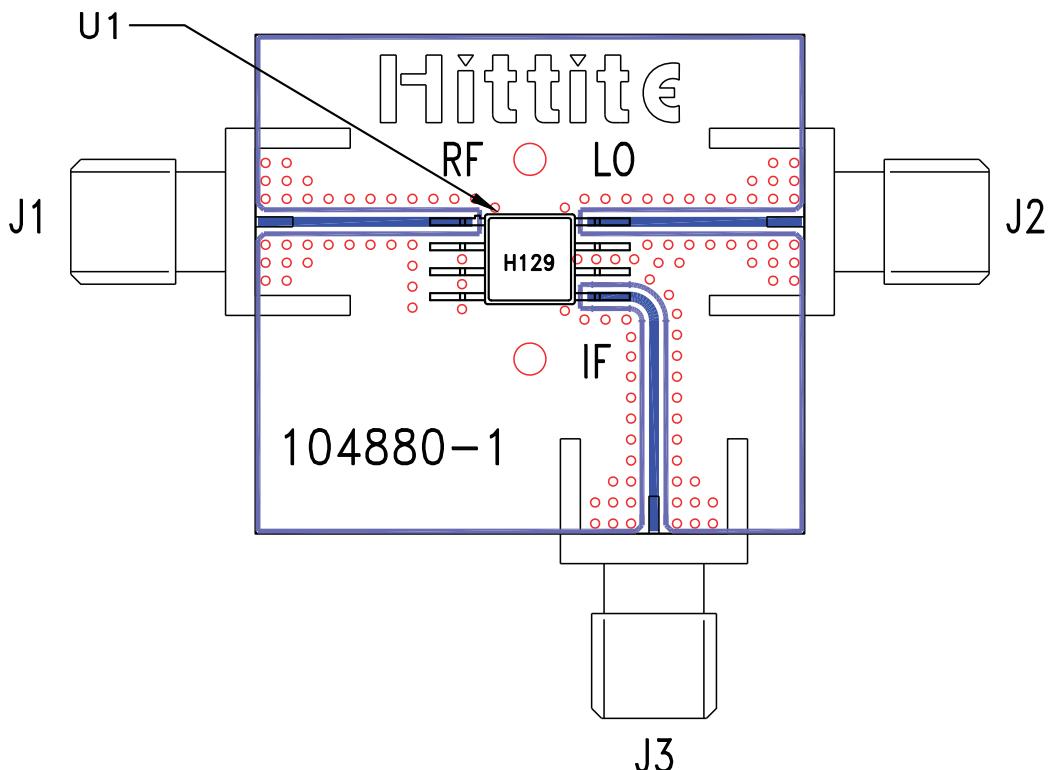
LO Drive (dBm)	Distortion		
	RF (f1) = 6.01 GHz	RF (f2) = 6.00 GHz	1 dB Compression
(dBm)	IP3 (dBm)	IP2 (dBm)	P1dB (dBm)
+7	14	59	8.5
+10	16	62	10
+13	18	65	11
+15	19	65	11


**GaAs MMIC SMT DOUBLE-BALANCED MIXER, 4 - 8 GHz**
**Absolute Maximum Ratings**

LO Drive	+27 dBm
Storage Temperature	-65 to +150 °C
Operating Temperature	-55 to +125 °C


**ELECTROSTATIC SENSITIVE DEVICE  
OBSERVE HANDLING PRECAUTIONS**
**Outline Drawing**

**NOTES:**

1. PACKAGE MATERIAL: ALUMINA LOADED BOROSILICATE GLASS.
2. LEAD, BASE, COVER MATERIAL: KOVAR™ (#7052 CORNING).
3. PLATING: ELECTROLYTIC GOLD 50 MICROINCHES MIN., OVER ELECTROLYTIC NICKEL 50 MICROINCHES MIN.
4. DIMENSIONS ARE IN INCHES [MILLIMETERS].
5. TOLERANCES: ±.005 [0.13] UNLESS OTHERWISE SPECIFIED.
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.


**Evaluation PCB**

**List of Materials for Evaluation PCB 104882 [1]**

Item	Description
J1 - J3	PCB Mount SMA RF Connector
U1	HMC129G8 Mixer
PCB [2]	104880 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.